

Electric insulation board or printed circuit board mfr. - by laminating non-woven glass cloth and glass fibre mat and impregnating with resin

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Patent Family:

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Abstract (Basic): JP 51070457 A

Method comprises (1) laminating a surface sheet of non-woven glass cloth of 10-100 g/m and a strand mat of glass fibre, (2) impregnating a thermosetting resin contg. inorganic filler into the laminated sheets and (3) heating and pressing the laminated sheets to form the laminated board. The board is used as an electric insulation board or a printed circuit board. The board is flat and has high mechanical strength.

Title Terms: ELECTRIC; INSULATE; BOARD; PRINT; CIRCUIT; BOARD; MANUFACTURE; LAMINATE; NON; WOVEN; GLASS; CLOTH; GLASS; FIBRE; MAT; IMPREGNATE; RESIN

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